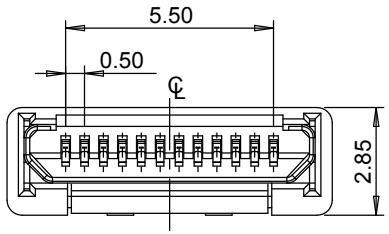
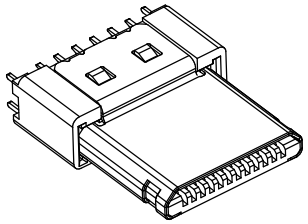
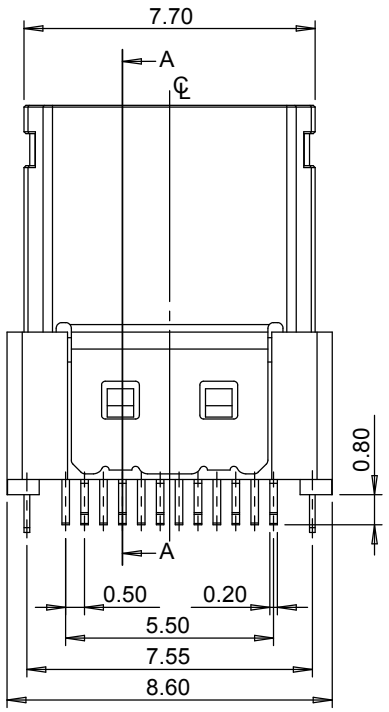
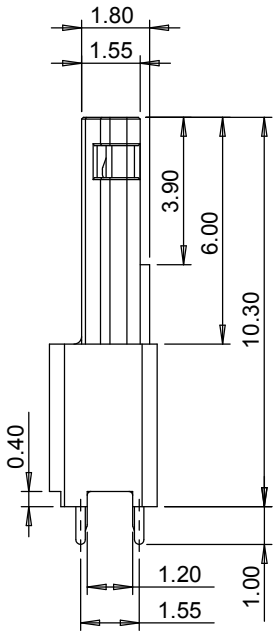
更改 REV	設 變 內 容 MODIFICATION
A	ECN01498
B	ECN01581

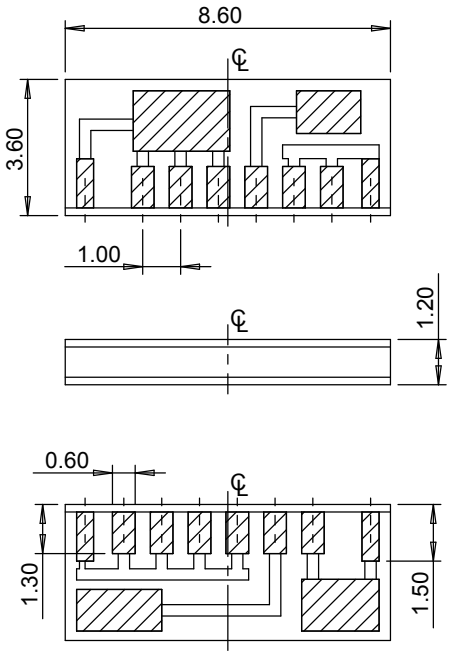
NOTES:
1. MATERIAL:
   INSULATOR: HIGH TEMPRATURE THERMOPLASTIC, UL94V-0,BLACK
   CONTACT: COPPER ALLOY
   COVER:STAINLESS STEEL
2. PLATING:
   CONTACT AREA:10μ" Au PLATED OVER Ni
   SOLDER AREA:Tin PLATED OVER Ni
3. PART NO: 7USMM-B0-X010
   PACKING:
   0:TRAY
   1:RELL











PCB LAYOUT

GENERIAL TOLERANCE	
X.± 0.50	X.°± 5°
.X± 0.30	.X°± 2°
.XX± 0.20	.XX°± 1°
	.XXX°± 0.5°

KINGCONN 皇海科技股份有限公司

名 稱(TITLE): microUSB 12PIN Connector

單 位(UNIT)	料 號(PART NO.)	圖 號(DWG NO.)
mm	7USMM-B0-X010	7USMM-B0-X010-B

審 核(APPROVAL)	核 對(CHECKED)	製 圖(DRAWN)	比 例 SCALE 5:1	張數 SHEET 1/1
			角 法 PROJ.	更 改 REV B